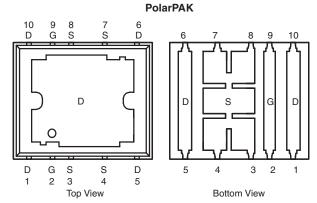


N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY							
		I _D (A)					
V _{DS} (V)	R _{DS(on)} (Ω) ^e	Silicon Limit	Package Limit	Q _g (Typ.)			
30	0.0017 at $V_{GS} = 10 \text{ V}$	202	60	75 nC			
30	0.0021 at $V_{GS} = 4.5 \text{ V}$	187	60	75110			

Package Drawing

www.vishay.com/doc?72945



Top surface is connected to pins 1, 5, 6, and 10

Ordering Information: SiE806DF-T1-E3 (Lead (Pb)-free)

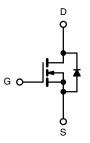
SiE806DF-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Gen II Power MOSFET
- Ultra Low Thermal Resistance Using Top-Exposed PolarPAK® Package for Double-Sided Cooling
- RoHS COMPLIANT HALOGEN FREE
- Leadframe-Based New Encapsulated Package
 - Die Not Exposed
 - Same Layout Regardless of Die Size
- Low Q_{ad}/Q_{as} Ratio Helps Prevent Shoot-Through
- 100 % R_q and UIS Tested
- Compliant to RoHS directive 2002/95/EC

APPLICATIONS

- DC/DC Conversion: Low-Side
- Synchronous Rectification



N-Channel MOSFET

For Related Documents www.vishay.com/ppg?73740

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	30	V	
Gate-Source Voltage		V _{GS}	± 12	V	
	T _C = 25 °C		202 (Silicon Limit)		
	1C = 25 C		60 ^a (Package Limit)		
Continuous Drain Current ($T_J = 150 ^{\circ}\text{C}$)	T _C = 70 °C	I _D	60 ^a		
	T _A = 25 °C		41.3 ^{b, c}		
	T _A = 70 °C		33 ^{b, c}	Α	
Pulsed Drain Current		I _{DM}	100		
Octions October Division Comment	T _C = 25 °C		60 ^a		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	4.3 ^{b, c}		
Single Pulse Avalanche Current	1 0.1 ml l	I _{AS}	50		
Avalanche Energy L = 0.1 mH		E _{AS}	125		
	T _C = 25 °C		125		
Maximum Dawar Dissination	T _C = 70 °C	P _D	80	w	
Maximum Power Dissipation	T _A = 25 °C		5.2 ^{b, c}	VV	
	T _A = 70 °C		3.3 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	
Soldering Recommendations (Peak Temperature) ^{d, e}			260		

- Package limited is 60 A. Surface Mounted on 1" x 1" FR4 board.
- See Solder Profile (www.vishay.com/doc?73257). The PolarPAK is a leadless package. The end of the lead terminal is exposed copper not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

SiE806DF

Vishay Siliconix



THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, b}	t ≤ 10 s	R _{thJA}	20	24		
Maximum Junction-to-Case (Drain Top)		R _{thJC} (Drain)	0.8	1	°C/W	
Maximum Junction-to-Case (Source) ^{a, c}	Steady State	R _{thJFC} (Source)	2.2	2.7		

Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. Maximum under Steady State conditions is 68 $^{\circ}\text{C/W}.$
- c. Measured at source pin (on the side of the package).

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		29		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1D = 230 μΑ		- 5.1			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	0.6	1.3	2	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1	—— иА	
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	25			Α	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 25 A		0.0014	0.0017		
		$V_{GS} = 4.5 \text{ V}, I_D = 25 \text{ A}$		0.0017	0.0021	Ω	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_{D} = 25 \text{ A}$		130		S	
Dynamic ^b							
Input Capacitance	C _{iss}			13000		pF	
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		1150			
Reverse Transfer Capacitance	C _{rss}			550			
Total Gate Charge	Qg	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 20 \text{ A}$		165	250	nC	
Total Gate Charge		V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 20 A		75	115		
Gate-Source Charge	Q_{gs}			23			
Gate-Drain Charge	Q_{gd}			9.5			
Gate Resistance	R_{g}	f = 1 MHz		0.9	1.35	Ω	
Turn-On Delay Time	t _{d(on)}			125	190		
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		160	240		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		85	130		
Fall Time	t _f			15	25	ns	
Turn-On Delay Time	t _{d(on)}			20	30	113	
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		50	75		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		85	130		
Fall Time	t _f			10	15		
Drain-Source Body Diode Characteristic	cs						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			60	А	
Pulse Diode Forward Current ^a	I _{SM}				100		
Body Diode Voltage	V _{SD}	I _S = 10 A		0.9	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			52	80	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 10 A, dl/dt = 100 A/μs, T _{.I} = 25 °C		55	105	nC	
Reverse Recovery Fall Time	t _a	1 _F = 10 A, αι/αι = 100 A/μ3, 1 J = 23 O		25		200	
Reverse Recovery Rise Time	t _b			27		ns	

Notes:

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

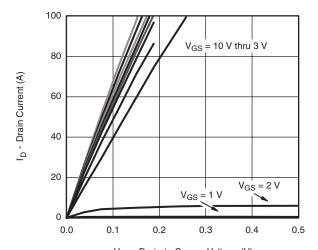
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



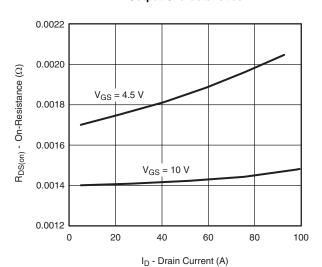




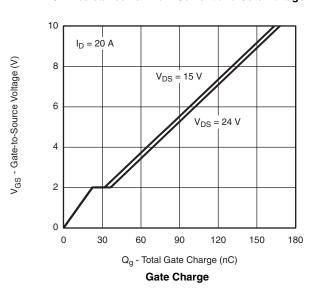
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



 V_{DS} - Drain-to-Source Voltage (V) Output Characteristics

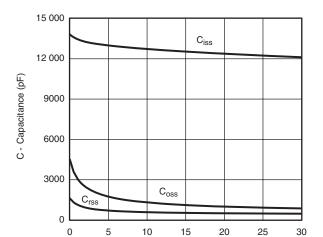


On-Resistance vs. Drain Current and Gate Voltage



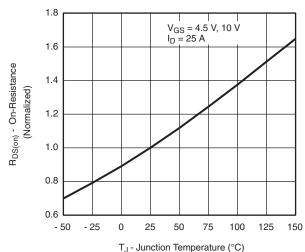
(Y) 12 $T_{C} = 125 \, ^{\circ}C$ $T_{C} = 25 \, ^{\circ}C$ $T_{C} = -55 \, ^{\circ}C$

V_{GS} - Gate-to-Source Voltage (V) **Transfer Characteristics**



V_{DS} - Drain-to-Source Voltage (V)

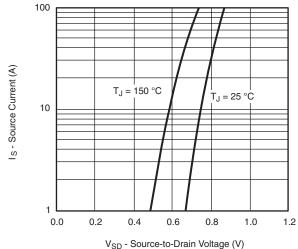




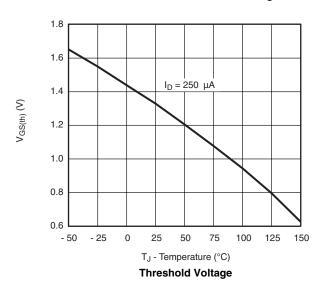
On-Resistance vs. Junction Temperature

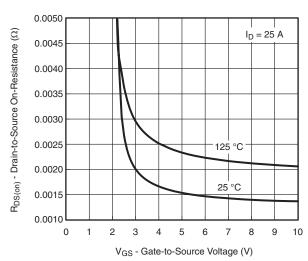
VISHAY

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

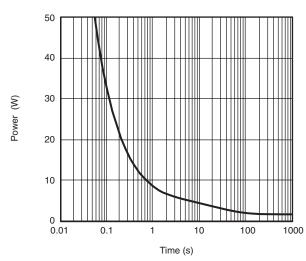


Source-Drain Diode Forward Voltage

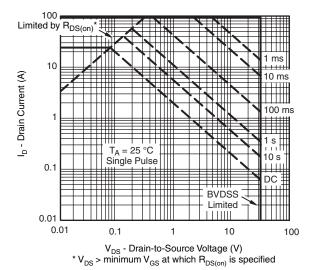




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

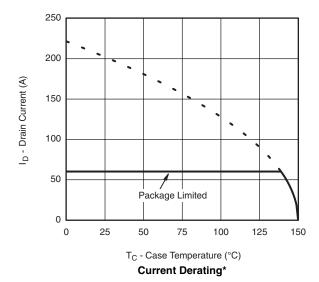


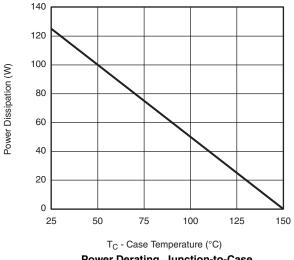
Safe Operating Area, Junction-to-Ambient





TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



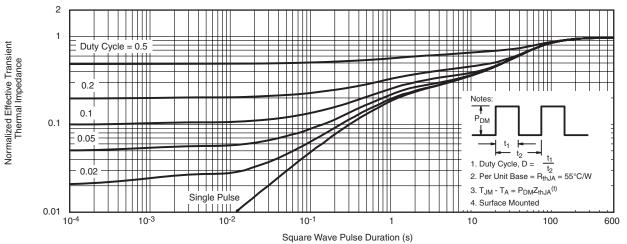


Power Derating, Junction-to-Case

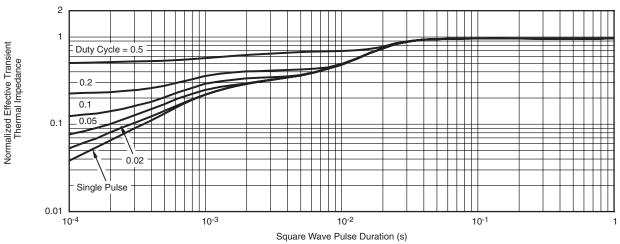
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



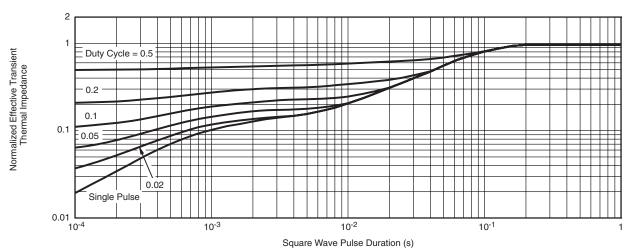
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case (Drain Top)



Normalized Thermal Transient Impedance, Junction-to-Source

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